



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Freescale Semiconductor

MPX4250
Rev 7, 1/2009

Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MPX4250 series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, particularly those employing a microcontroller or microprocessor with A/D inputs. This transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high-level analog output signal that is proportional to the applied pressure. The small form factor and high reliability of on-chip integration make the Freescale sensor a logical and economical choice for the automotive system engineer.

Features

- Differential and Gauge Applications Available
- 1.4% Maximum Error Over 0° to 85°C
- Patented Silicon Shear Stress Strain Gauge
- Temperature Compensated Over -40° to +125°C
- Offers Reduction in Weight and Volume Compared to Existing Hybrid Modules
- Durable Epoxy Unibody Element

MPX4250 Series

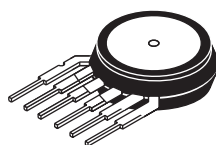
0 to 250 kPa (0 to 36.3 psi)
0.2 to 4.9 V Output

Application Examples

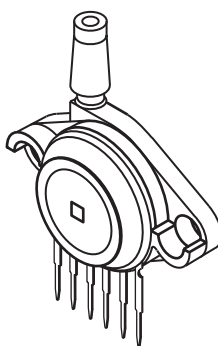
- Ideally Suited for Microprocessor or Microcontroller-Based Systems

ORDERING INFORMATION									
Device Name	Package Options	Case No.	# of Ports			Pressure Type			Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
Unibody Package (MPX4250 Series)									
MPX4250D	Tray	867	•				•		MPX4250D
MPX4250GP	Tray	867B		•		•			MPX4250GP
MPX4250DP	Tray	867C			•		•		MPX4250DP

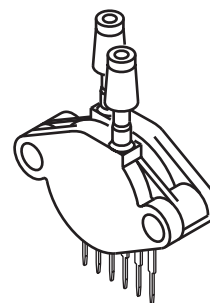
UNIBODY PACKAGES



MPX4250D
CASE 867



MPX4250GP
CASE 867B



MPX4250DP
CASE 867C

Operating Characteristics

Table 1. Operating Characteristics ($V_S = 5.1$ Vdc, $T_A = 25^\circ\text{C}$ unless otherwise noted, $P_1 > P_2$.
Decoupling circuit shown in [Figure 3](#) required to meet electrical specifications.)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure Range ⁽¹⁾	P_{OP}	0	—	250	kPa
Supply Voltage ⁽²⁾	V_S	4.85	5.1	5.35	Vdc
Supply Current	I_o	—	7.0	10	mAdc
Minimum Pressure Offset @ $V_S = 5.1$ Volts ⁽³⁾ (0 to 85°C)	V_{off}	0.139	0.204	0.269	Vdc
Full Scale Output @ $V_S = 5.1$ Volts ⁽⁴⁾ (0 to 85°C)	V_{FSO}	4.844	4.909	4.974	Vdc
Full Scale Span @ $V_S = 5.1$ Volts ⁽⁵⁾ (0 to 85°C)	V_{FSS}	—	4.705	—	Vdc
Accuracy ⁽⁶⁾ (0 to 85°C)	—	—	—	± 1.4	% V_{FSS}
Sensitivity	$\Delta V/\Delta P$	—	18.8	—	mV/kPa
Response Time ⁽⁷⁾	t_R	—	1.0	—	ms
Output Source Current at Full Scale Output	I_{o+}	—	0.1	—	mAdc
Warm-Up Time ⁽⁸⁾	—	—	20	—	ms
Offset Stability ⁽⁹⁾	—	—	± 0.5	—	% V_{FSS}

- 1.0 kPa (kiloPascal) equals 0.145 psi.
- Device is ratiometric within this specified excitation range.
- Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
- Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
- Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
 - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
 - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
 - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C .
 - TcSpan: Output deviation over the temperature range of 0 to 85°C , relative to 25°C .
 - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C , relative to 25°C .
 - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS} , at 25°C .
- Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
- Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P _{MAX}	1000	kPa
Storage Temperature	T _{STG}	−40 to +125	°C
Operating Temperature	T _A	−40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

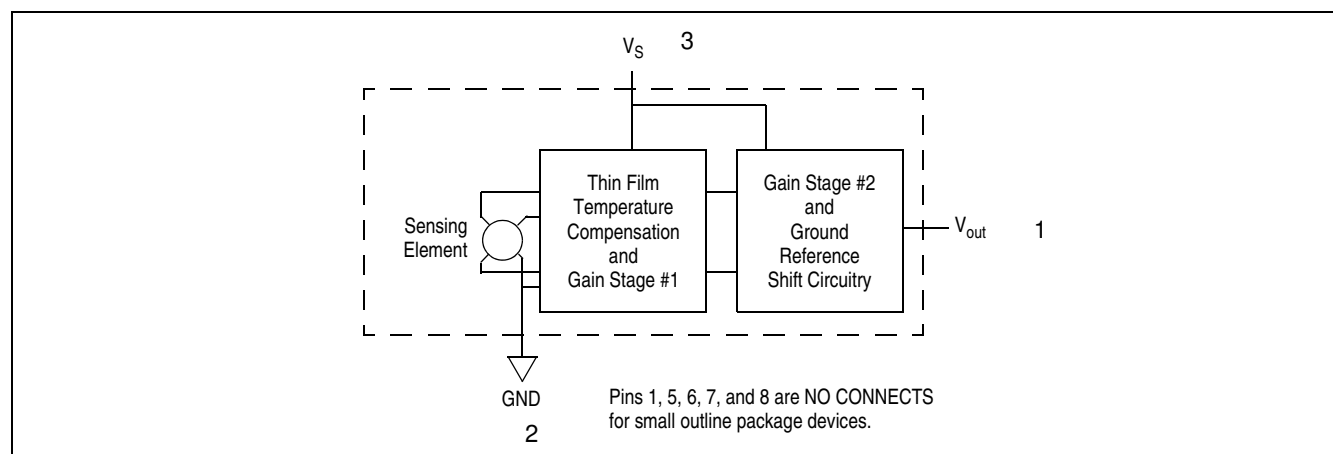


Figure 1. Fully Integrated Pressure Sensor Schematic

On-chip Temperature Compensation and Calibration

Figure 2 illustrates the differential/gauge pressure sensing chip in the basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPX4250 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor

performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 3 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range

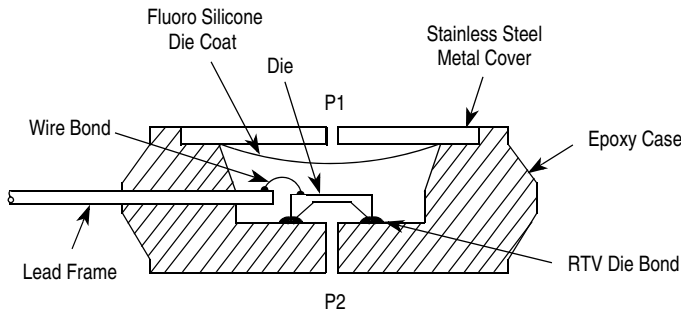


Figure 2. Cross Sectional Diagram (not to scale)

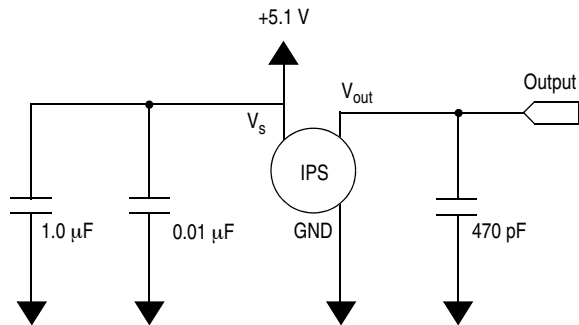


Figure 3. Recommended Power Supply Decoupling and Output Filtering
(For additional output filtering, please refer to Application Note AN1535)

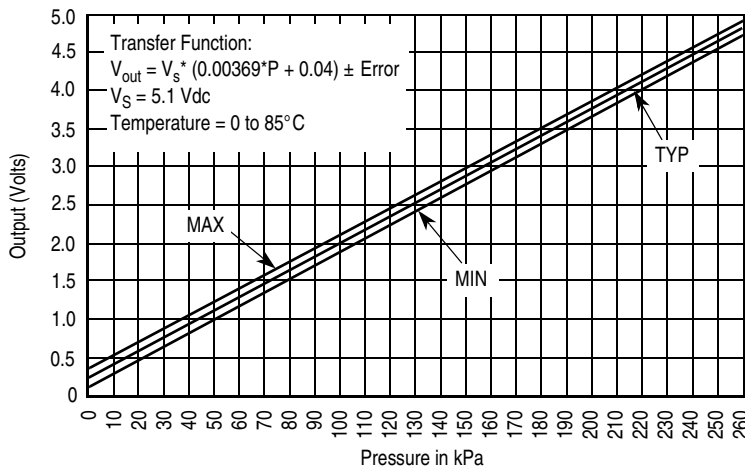
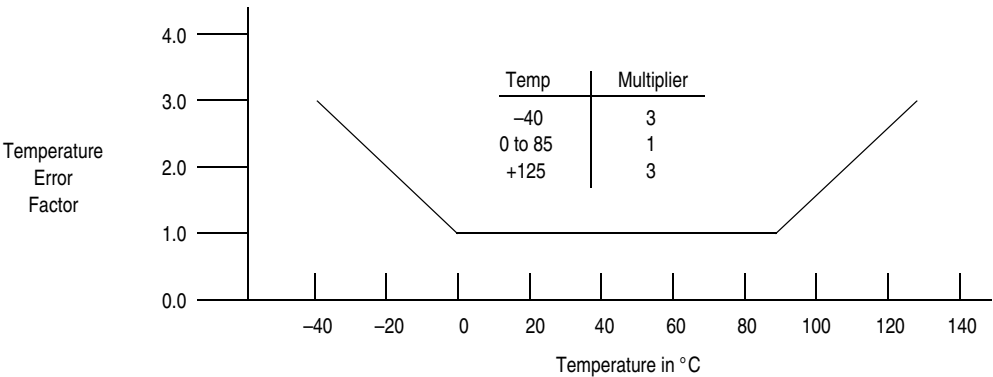


Figure 4. Output versus Absolute Pressure

Transfer Function (MPX4250)

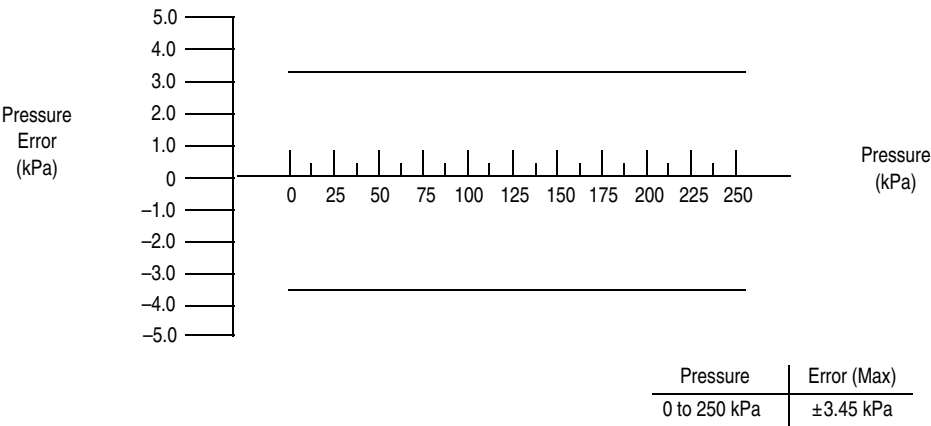
Nominal Transfer Value: $V_{out} = V_S \times (0.00369 \times P + 0.04)$
 $\pm (\text{Pressure Error} \times \text{Temp. Factor} \times 0.00369 \times V_S)$
 $V_S = 5.1 \pm 0.25 \text{ Vdc}$

Temperature Error Band

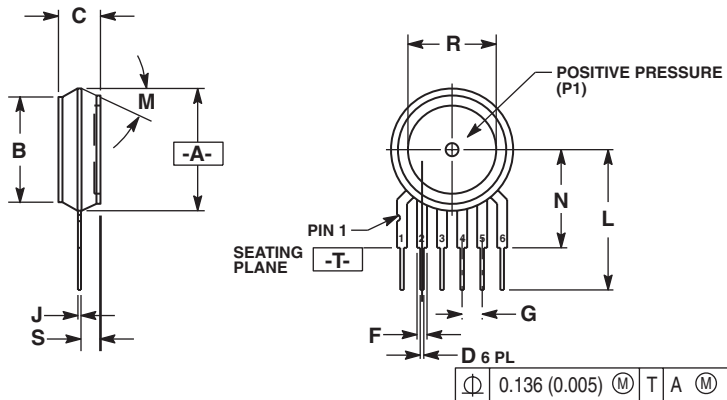


NOTE: The Temperature Multiplier is a linear response from 0°C to -40°C and from 85°C to 125°C.

Pressure Error Band



PACKAGE DIMENSIONS



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

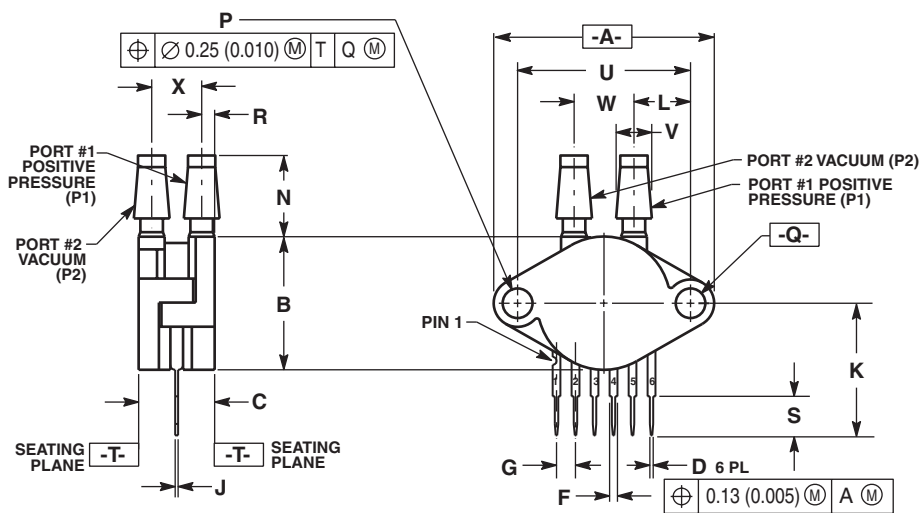
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.027	0.033	0.68	0.84
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
S	0.090	0.105	2.29	2.66

STYLE 1:
PIN 1. VOUT
2. GROUND
3. VCC
4. V1
5. V2
6. VEX

STYLE 2:
PIN 1. OPEN
2. GROUND
3. -VOUT
4. VSUPPLY
5. +VOUT
6. OPEN

STYLE 3:
PIN 1. OPEN
2. GROUND
3. +VOUT
4. +VSUPPLY
5. -VOUT
6. OPEN

BASIC ELEMENT (D) CASE 867-08 ISSUE N



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.

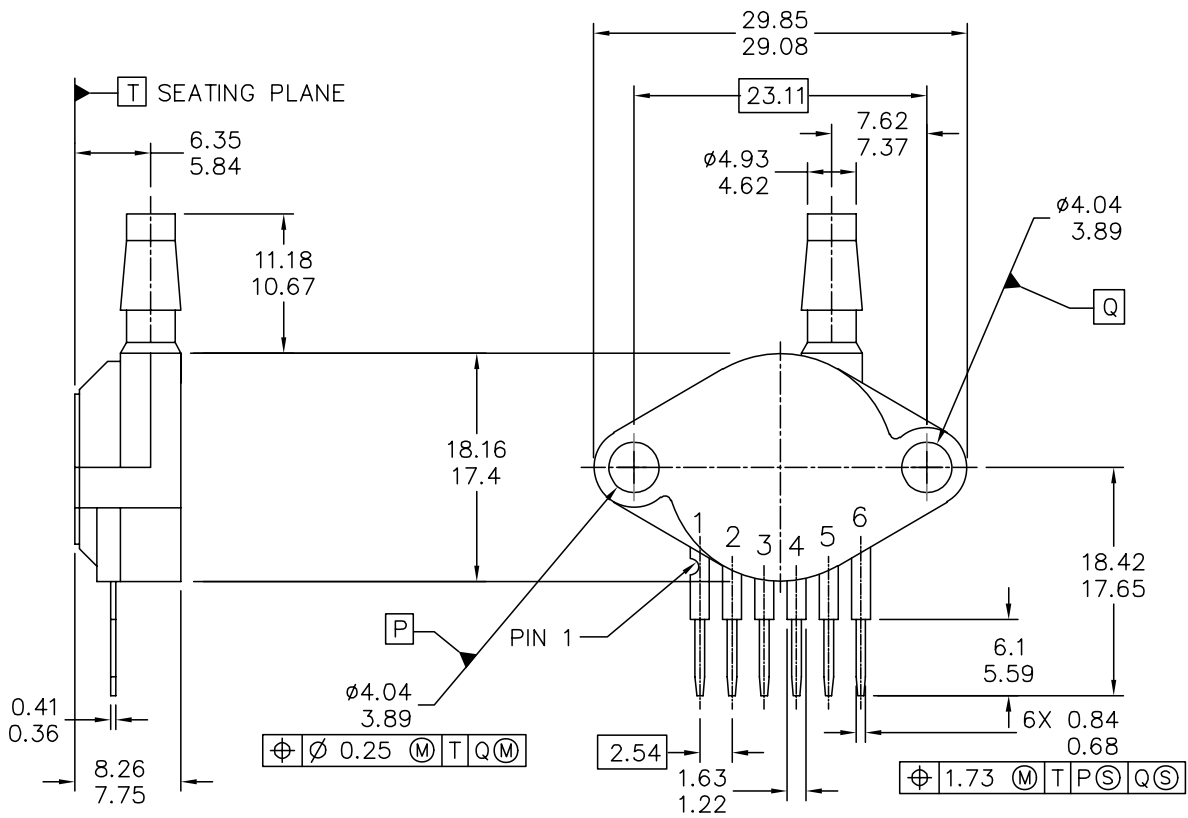
DIM	INCHES			MILLIMETERS	
	MIN	MAX	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85	
B	0.685	0.715	17.40	18.16	
C	0.405	0.435	10.29	11.05	
D	0.027	0.033	0.68	0.84	
F	0.048	0.064	1.22	1.63	
G	0.100 BSC		2.54 BSC		
J	0.014	0.016	0.36	0.41	
K	0.695	0.725	17.65	18.42	
L	0.290	0.300	7.37	7.62	
N	0.420	0.440	10.67	11.18	
P	0.153	0.159	3.89	4.04	
Q	0.153	0.159	3.89	4.04	
R	0.063	0.083	1.60	2.11	
S	0.220	0.240	5.59	6.10	
U	0.910 BSC		23.11 BSC		
V	0.182	0.194	4.62	4.93	
W	0.310	0.330	7.87	8.38	
X	0.248	0.278	6.30	7.06	

STYLE 1:

PIN 1. VOUT
2. GROUND
3. VCC
4. V1
5. V2
6. VEX

PRESSURE AND VACUUM SIDE DUAL PORTED (DP) CASE 867C-05 ISSUE F

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: SENSOR, 6 LEAD UNIBODY CELL, AP & GP 01ASB09087B			DOCUMENT NO: 98ASB42796B		REV: G
			CASE NUMBER: 867B-04		28 JUL 2005
			STANDARD: NON-JEDEC		

PAGE 1 OF 2

PRESSURE SIDE PORTED (GP)
CASE 867B-04
ISSUE G

MPX4250



PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. 867B-01 THRU -3 OBSOLETE, NEW STANDARD 867B-04.

STYLE 1:

- PIN 1: V OUT
2: GROUND
3: VCC
4: V1
5: V2
6: V EX

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: SENSOR, 6 LEAD UNIBODY CELL, AP & GP 01ASB09087B			DOCUMENT NO: 98ASB42796B		REV: G
			CASE NUMBER: 867B-04		28 JUL 2005
			STANDARD: NON-JEDEC		

**PRESSURE SIDE PORTED (GP)
CASE 867B-04
ISSUE G**

How to Reach Us:

Home Page:

www.freescale.com

Web Support:

<http://www.freescale.com/support>

USA/Europe or Locations Not Listed:

Freescale Semiconductor, Inc.
Technical Information Center, EL516
2100 East Elliot Road
Tempe, Arizona 85284
1-800-521-6274 or +1-480-768-2130
www.freescale.com/support

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
www.freescale.com/support

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor China Ltd.
Exchange Building 23F
No. 118 Jianguo Road
Chaoyang District
Beijing 100022
China
+86 010 5879 8000
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or +1-303-675-2140
Fax: +1-303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2009. All rights reserved.